Customer Information Notification

201807032I

Issue Date: 17-Aug-2018
Effective Date: 17-Sep-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Management Summary

i.MX6Dual / Quad Plus NXP-ATTJ Final test to STATS ChipPAC Singapore Final test Expansion

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[X] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

i.MX6Dual / Quad Plus NXP-ATTJ Final Test to STATS ChipPAC Singapore Final Test Expansion

Description

NXP Semiconductors announces the Final Test site expansion for the MCIMX6Q/ MCIMX6D associated with this notification, from the current NXP ATTJ, Tianjin, China Final Test site to the STATS ChipPAC, Singapore, Final Test site.

Final Test site expansion was successfully qualified adhering to NXP specifications.

Please see the attached file for additional details.

Reason

Qualification of STATS ChipPAC, Singapore is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products
Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products
NXP will reserve the right to ship from any location based on market demand situation.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Liguang Han
Position Product Engineer

e-mail address liguang.han@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MCIMX6DP5EYM1AB	935357835557	MCIMX6DP5EYM1AB	I.MX 6DP ROM Perf Enhan	SOT1642-2	LFBGA624	ASM	BL Microcontrollers
MCIMX6QP7CVT8AA	935312744557	MCIMX6QP7CVT8AA	i.MX 6QP Rev 1.0	SOT1643-1	FBGA624	RFS	BL Microcontrollers
MCIMX6QP5EYM1AA	935316001557	MCIMX6QP5EYM1AA	i.MX 6QP Rev 1.0	SOT1642-2	LFBGA624	RFS	BL Microcontrollers
MCIMX6QP7CVT8AB	935356641557	MCIMX6QP7CVT8AB	i.MX 6QP ROM Enhan	SOT1643-1	FBGA624	RFS	BL Microcontrollers
MCIMX6QP5EYM1AB	935357836557	MCIMX6QP5EYM1AB	i.MX 6QP ROM Perf Enhan	SOT1642-2	LFBGA624	RFS	BL Microcontrollers
MCIMX6DP7CVT8AA	935315902557	MCIMX6DP7CVT8AA	I.MX 6DP Rev 1.0	SOT1643-1	FBGA624	RFS	BL Microcontrollers
MCIMX6DP5EYM1AA	935316005557	MCIMX6DP5EYM1AA	I.MX 6DP Rev 1.0	SOT1642-2	LFBGA624	RFS	BL Microcontrollers
MCIMX6DP7CVT8AB	935356639557	MCIMX6DP7CVT8AB	I.MX 6DP ROM Perf Enhan	SOT1643-1	FBGA624	RFS	BL Microcontrollers